



Silver Conductive Epoxy Adhesive

Good Conductivity / Slow Cure

8331S Technical Data Sheet

Description

The 8331S Silver Conductive Epoxy Adhesive: Good Conductivity / Slow Cure is an economical electronic grade epoxy that combines long working time and good conductivity with ease of use. It has a convenient 1-to-1 mix ratio and 4–5 hour work life. Once mixed, it behaves essentially like a 1-part adhesive for the duration of a work shift. However, unlike 1-part adhesives that often require high heat of 130 to 170 °C, it will cure at 65 °C in less than 2 hour. The cured conductive adhesive bonds very well to most substrates used in electronic assemblies; resists thermal and mechanical shocks; and provides the low resistivity needed for many operating conditions. The 8331S epoxy adhesive provides high conductivity seals, bonds, and traces for electronic devices in automobile, aerospace, marine, communication, and industrial control.

Applications & Usages

The 8331S epoxy has many uses in the production, repair and assembly of electronics in microelectronics and optoelectronics. It has been designed for production environments as a replacement for one part silver conductive epoxy systems when high cure temperatures can potentially damage heat sensitive components, or where frozen storage requirements or shelf life of one part epoxies are a concern. Like all conductive epoxies, it operates as a lead free replacement for metal solder, and it excels at bonding heat-sensitive electronic components. It also provides excellent EMI/RFI shielding and is very effective at filling seams between metal plates.

Benefits and Features

- **Good 0.0060 Ω·cm electrical resistivity and 0.85 W/(m·K) thermal conductivity**
- **Easy 1:1 mix ratio and long working time**—may be mixed once and then used as a 1-part epoxy for a four hour production shift
- **Optimal cure temperature of only 65 °C**—lower than most 1-part epoxies and suitable for use on heat sensitive components
- **Stores and ships at room temperature**—no freezing or dry ice required
- **Very long shelf life of at least two years**—even when stored at room temperature
- **Strong water and chemical resistance** to brine, acids, bases, and aliphatic hydrocarbons
- **Excellent adhesion to most electronic substrates**

ENVIRONMENT
✓ RoHS
✓ REACH compliant

Curing & Work Schedule

Properties	Value
Working Life ^{a)}	240 min
Shelf Life	≥3 y
Full Cure @65 °C [149 °F]	120 min
Full Cure @80 °C [176 °F]	60 min
Full Cure @100 °C [212 °F]	40 min

a) Cure and life values 5 g unless stated otherwise.

Temperature Service Range

Properties	Value
Constant Service Temp.	-40 °C to 150 °C [-40 °F to 302 °F]
Storage Temperature of Unmixed Parts	22 to 27 °C [72 to 80 °F]

Properties of Cured 8331S

Physical Properties	Method	Value ^{a)}
Color	Visual	Silver Grey
Density @ 25 °C [77 °C]		2.19 g/cm ³
Hardness	(Shore D durometer)	73D
Tensile Strength	ASTM D 638	14 N/mm ² [2 000 lb/in ²]
Elongation	"	5.3%
Young's Modulus	"	760 MPa
Lap Shear Strength (Stainless Steel 304)	ASTM D 1002	1.1 N/mm ² [160 lb/in ²]
Lap Shear Strength (Aluminum 5052)	ASTM D 1002	4.8 N/mm ² [690 lb/in ²]
Compressive Strength	ASTM D 695	65 N/mm ² [9 400 lb/in ²]
Flexural Strength	ASTM D 790	d)
Solderable		No
Outgassing (Total Mass Loss) @ 24 h	ASTM E 595	0.43%
Water vapor release	"	0.27%
Collectable Volatile Condensable Material	"	0.04%
Water absorption		0.12%
Electric Properties ^{b)}	Method	Value
Volume Resistivity After 65 °C [149 °F] cure	Method 5011.5 in MIL-STD-883H	0.0060 Ω·cm
Surface Resistance After 25 °C [149 °F] cure after 96 h	Square Probe	~0.35 Ω/sq
After 65 °C [149 °F] cure after 1 h	Square Probe	0.25–0.40 Ω/sq
After 80 °C [176 °F] cure	Square Probe	0.15–0.20 Ω/sq
After 100 °C [212 °F] cure	Square Probe	0.11–0.15 Ω/sq
Thermal Properties	Method	Value
Thermal Conductivity @25 °C	ASTM E 1461	0.850 W/(m·K)
@50 °C	"	0.826 W/(m·K)
@100 °C	"	0.961 W/(m·K)
Glass Transition Temperature (T _g)	ASTM D 3418	34 °C [93 °F]
CTE prior T _g ^{c)}	ASTM E 831	78 ppm/°C
CTE after T _g ^{c)}	ASTM E 831	158 ppm/°C
Specific Heat @25 °C [77 °F]		0.904 J/(g·K)

Note: Specifications are for epoxy samples that were cured at 80 °C for 60 minutes. Additional curing time at room temperature was given to allow for optimum curing. Samples were conditioned at 23 °C and 50% RH prior to most tests.

a) N/mm² = mPa; lb/in² = psi

b) The uncured epoxy mixture does not conduct electricity well and can have high resistance. To attain stated resistivity, ensure that the mix ratio is followed and that the product is fully cured by heat curing.

c) Coefficient of Thermal Expansion (CTE) units are in ppm/°C = in/in/°C × 10⁻⁶ = unit/unit/°C × 10⁻⁶

d) To be determined



ISO 9001 Registered Quality System.
Burlington, Ontario, Canada QMI File # 004008

Silver Conductive Epoxy Adhesive

Good Conductivity / Slow Cure

8331S Technical Data Sheet

8331S

Properties of Uncured 8331S

<i>Physical Property</i>	<i>Mixture (1A:1B)</i>	
Color	Silver Grey	
Density ^{a)}	2.43 g/mL	
Mix Ratio by volume (A:B)	1:00:1.00	
Mix Ratio by weight (A:B)	1.17:1.00	
Solids Content (w/w)	100%	
<i>Physical Property</i>	<i>Part A</i>	<i>Part B</i>
Color	Silver Grey	Silver Grey
Density	2.61 g/mL	2.25 g/mL
Flash Point	>127 °C [261 °F]	>93 °C [200 °F]
Resistivity of uncured material	Off-scale (no reading)	Off-scale (no reading)

a) Calculated value based on measures densities of each part

Extrusion Rate

The extrusion rate for a ¼" nozzle for each adhesive parts with respect to pressure are given below. For extrusion rates with respect to other nozzle diameters, contact us at support@mgchemicals.com.

8331S Extrusion Rates for Part A and B

<i>Pressure</i> lb/in ²	<i>Rate Part A</i> g/min	<i>Rate Part B</i> g/min
40	521	44
50	628	86
60	731	128
70	832	170
80	931	211
90	1027	223

Note: Nozzle diameter = ¼"

Principal Components

Name

Part A: Epoxide Resin
Metallic Silver
Part B: Aliphatic Amines
Metallic Silver

CAS Number

28768-32-3 + 17557-23-3
7440-22-4
68082-29-1, 112-24-3, 68541-13-9, 4246-51-9
7440-22-4



Silver Conductive Epoxy Adhesive


Good Conductivity / Slow Cure

8331S Technical Data Sheet

Compatibility

Adhesion—As seen in the substrate adhesion table, the 8331S epoxy adheres to most materials found on printed circuit assemblies; however, it is not compatible with contaminants like water, oil, and greasy flux residues that may affect adhesion. If contamination is present, clean the printed circuit assembly with electronic cleaner such as MG Chemicals 4050 Safety Wash, 406B Superwash, or 824 Isopropyl Alcohol.

Substrate Adhesion in Decreasing Order

<i>Physical Properties</i>	<i>Adhesion</i>
Steel	Stronger  Weaker
Aluminum	
Fiberglass	
Wood	
Paper, Fiber	
Glass	
Rubber	
Polycarbonate	
Acrylic	
Polypropylene ^{a)}	

a) Does not bond to polypropylene

Storage

Store between 22 and 27 °C [72 and 80 °F] in dry area away from sunlight. Prolonged storage or storage at or near freezing temperatures can result in crystallization. If crystallization occurs, reconstitute the component to its original state by temporarily warming it to 50 to 60 °C [122 to 140 °F]. To ensure full homogeneity, stir thoroughly the warm component, reincorporating all settled material. Re-secure container lid and let cool down before use.

Health, Safety, and Environmental Awareness

Please see the 8331S **Safety Data Sheet** (SDS) parts A and B for more details on transportation, storage, handling and other security guidelines.

Health and Safety: The 8331S parts can ignite if the liquid is both heated and exposed to flames or sparks.

Wear safety glasses or goggles and disposable polyvinyl chloride, neoprene, or nitrile gloves while handling liquids. Part B in particular causes skin burns and may cause sensitization if exposed over a long period of time. The epoxy will not wash off once cured: wear protective work clothing. Wash hands thoroughly after use or if skin contact occurs. Do not ingest.

Use in well-ventilated area since vapors may cause irritation of the respiratory tract and cause respiratory sensitization in susceptible individuals.

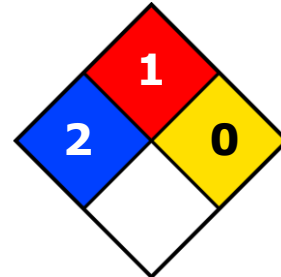
The cured epoxy resin presents no known hazard.

Part A

HMIS® RATING

HEALTH:	* 2
FLAMMABILITY:	1
PHYSICAL HAZARD:	0
PERSONAL PROTECTION:	

NFPA® 704 CODES

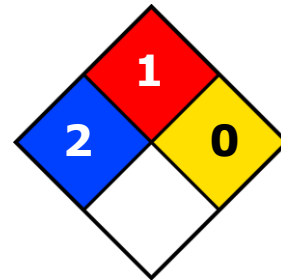


Part B

HMIS® RATING

HEALTH:	* 2
FLAMMABILITY:	1
PHYSICAL HAZARD:	0
PERSONAL PROTECTION:	

NFPA® 704 CODES



Approximate HMIS and NFPA Risk Ratings Legend:

0 (Low or none); 1 (Slight); 2 (Moderate); 3 (Serious); 4 (Severe)

Application Instructions

Follow the procedure below for best results. Heat cure is recommended to get the best possible conductivity.

To prepare 1:1 (A:B) epoxy mixture

1. Remove cap or cover.
2. Measure **one** part by volume of **A**.
3. Measure **one** part by volume of **B**.
4. Thoroughly mix the parts together with a stir stick until homogeneous.
5. Apply to with an appropriate sized stick for the application area.

NOTE: Remember to recap the syringe or container promptly after use.

TIP: Due to the high viscosity and abrasiveness of the silver filler, you may preheat part A and part B to increase the flow and improve air release.



ISO 9001 Registered Quality System.
Burlington, Ontario, Canada QMI File # 004008

Silver Conductive Epoxy Adhesive

Good Conductivity / Slow Cure

8331S Technical Data Sheet

8331S

To heat cure the 8331S epoxy

Put in oven at 65 °C [149 °F] for 120 minutes. For optimum conductivity and faster cure, heat cure at temperatures up to 100 °C.

TIP: Hair dryers are normally rated not to exceed 60 °C, so they can generally be used to accelerate the cure.

You can cure the epoxy faster by using higher temperatures of up to 100 °C [302 °F].

ATTENTION: Keep the curing temperature well below temperature limit of heat sensitive components that may be present. As a guideline, remember that commercial grade devices normally can be safely operated up to 70 °C, industrial grade up to 85 °C, and military grade up to 175 °C.

ATTENTION: Heat guns can easily exceed the temperature limits for your assembly: they should not be used.

Packaging and Supporting Products

<i>Cat. No.</i>	<i>Form</i>	<i>Net Volume</i>		<i>Net Weight</i>		<i>Shipping Weight</i>	
8331S-15G	Paste	6 mL	0.2 fl.oz	15 g	0.47 oz	400 g ^{a)}	0.9 lb ^{a)}
8331S-50ML	Paste	50 mL	1.7 fl oz	117 g	3.8 oz	2.0 kg ^{a)}	4.4 lb ^{a)}
8331S-200ML	Paste	200 mL	7 fl oz	254 kg	15.6 oz	0.6 kg	1.3 lb

a) Pack of ten

Technical Support

Contact us regarding any questions, improvement suggestions, or problems with this product. Application notes, instructions, and FAQs are located at www.mgchemicals.com.

Email: support@mgchemicals.com

Phone: 1-800-340-0772 (Canada, Mexico & USA)
1-905-331-1396 (International)

Fax: 1-905-331-2862 or 1-800-340-0773

Mailing address: **Manufacturing & Support**
1210 Corporate Drive
Burlington, Ontario, Canada
L7L 5R6

Head Office
9347-193rd Street
Surrey, British Columbia, Canada
V4N 4E7



ISO 9001 Registered Quality System.
Burlington, Ontario, Canada QMI File # 004008

Silver Conductive Epoxy Adhesive *Good Conductivity / Slow Cure* 8331S Technical Data Sheet

8331S

Warranty

M.G. Chemicals Ltd. warrants this product for 12 months from the date of purchase by the end user. *M.G. Chemicals Ltd.* makes no claims as to shelf life of this product for the warranty. The liability of *M.G. Chemicals Ltd.* whether based on its warranty, contracts, or otherwise shall in no case include incidental or consequential damage.

Disclaimer

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. *M.G. Chemicals Ltd.* does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.